

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Abu K. Eghan et al.  
Assignee: Xilinx, Inc.  
Title: High Performance Flipchip Package That  
Incorporates Heat Removal With Minimal  
Thermal Mismatch

Serial No.:	09/879,875	File Date:	6/11/01
Examiner:	Evan T. Pert	Art Unit:	2829
Docket No.:	X-901 US	Conf. No.:	4969

Box AF  
COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

AFTER FINAL AMENDMENT AND RESPONSE UNDER 37 CFR 1.112

Dear Sir:

In response to the Final Office Action mailed from the Patent Office January 17, 2003, please enter the following amendment and consider the following remarks. This communication is being filed prior to the two month period for response of March 17, 2003.

Applicants submit that the current office action was prematurely made final because the Examiner presented new grounds of rejection not necessitated by Applicants' amendment. Therefore, Applicants request the withdrawal of the finality of the present office action. In the alternative, Applicants submit that the following amendments are being made to place the claims in condition for allowance and/or to present the claims in better condition for appeal. Because each of the presently presented claim limitations have been present in the instant application, Applicants submit consideration of this amendment will not necessitate an additional search.